



Click [here](#) for the 3D model.

| Dimensions |                  |
|------------|------------------|
| Chip Size  | 0603             |
| L          | 1.6mm +/-0.15mm  |
| W          | 0.8mm +/-0.15mm  |
| T          | 0.8mm +/-0.15mm  |
| S          | 0.7mm MIN        |
| B          | 0.35mm +/-0.15mm |

| Packaging Specifications |                        |
|--------------------------|------------------------|
| Packaging                | T&R, 330mm, Paper Tape |
| Packaging Quantity       | 15000                  |

| General Information |   |
|---------------------|---|
| Series              | SMD Comm X7R                            |
| Style               | SMD Chip                                |
| Description         | SMD, MLCC, Temperature Stable, Class II |
| Features            | Temperature Stable, Class II            |
| RoHS                | Yes                                     |
| Termination         | Tin                                     |
| Marking             | No                                      |
| AEC-Q200            | No                                      |
| Component Weight    | 7.3 mg                                  |
| Shelf Life          | 78 Weeks                                |
| MSL                 | 1                                       |

| Specifications   |   |
|--|---|
| Capacitance  | 0.1uF   |
| Measurement Condition  | 1 kHz 1.0Vrms                                 |
| Capacitance Tolerance  | 10%   |
| Voltage DC   | 16 VDC  |
| Dielectric Withstanding Voltage                                    | 40 VDC  |
| Temperature Range  | -55/+125°C                                    |
| Temperature Coefficient  | X7R   |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms                             |
| Dissipation Factor   | 3.5% 1kHz 1.0Vrms                             |
| Aging Rate   | 3% Loss/Decade Hour: Referee Time is 48 Hours |
| Insulation Resistance  | 5 GOhms                                       |